

Inline system VADU 300

Automated soldering with vacuum

Efficient soldering system for series production

The soldering system VADU 300 is designed for highly efficient series production with internal substrate handling and inline carrier transfer. According to customer requirements the loading or reloading operations can be realized manually or automatically. The system is available in two alternative configurations as paste or as preform soldering system (with integrated formic acid process). The soldering system is characterized by its easy maintainability and ergonomic operation.

With its three process chambers, the vacuum supported soldering process and the internal substrate handling the VADU 300 system is optimized for highly productive void-free quality series production.

Technical data

Process area: L 410 x W 280 mm (e.g. 4 boards 5 x 7")

Substrate height: max. 100 mm

Dimensions of soldering system: approx. L 2,300 x W 1,600 x H 1,800 mm

Dimensions of pump stand: approx. L 1,000 x W 700 x H 1,800 mm

Power supply: 3 x 400 V, 50/60 Hz

Power input: 25 kVA

Weight (without pump stand): approx. 1,450 kg

System advantages

- Void-free solder connections
- Soldering with preforms or paste
- Operation with inert or forming gas
- Formic acid process
- Flux management
- Soldering temperatures up to 400 °C
- Vacuum supported soldering
- Individual soldering profiles (e.g. acc. to IPC/JEDEC)
- Low energy and media consumption
- Clearly arranged touch screen panel
- Maintenance friendly process technology

Options

- Integration into production lines (e.g. systems with surrounding transfer units or systems to link-up with pick-and-place machines)
- Application-optimized carriers
- Camera system for process monitoring



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